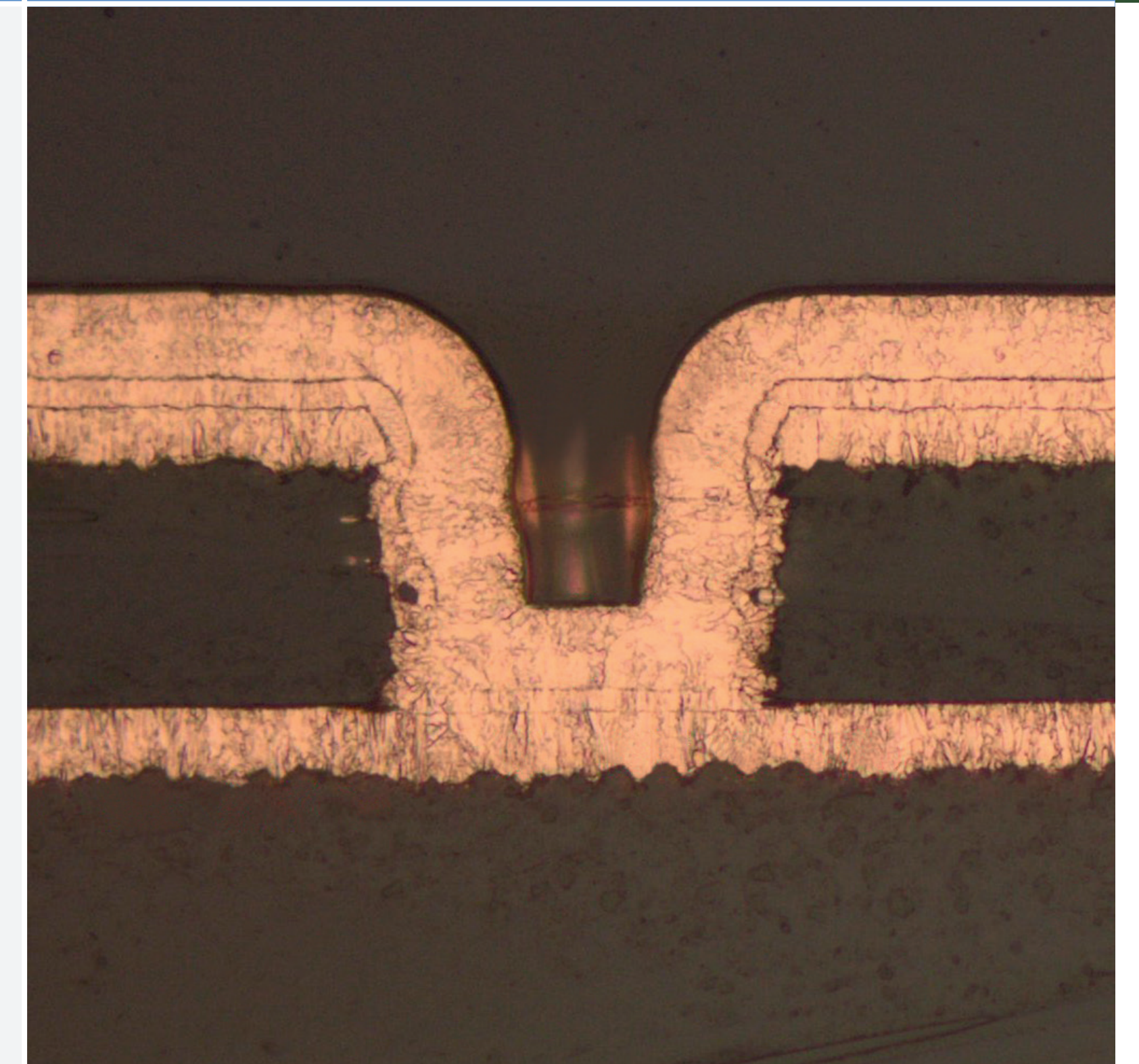
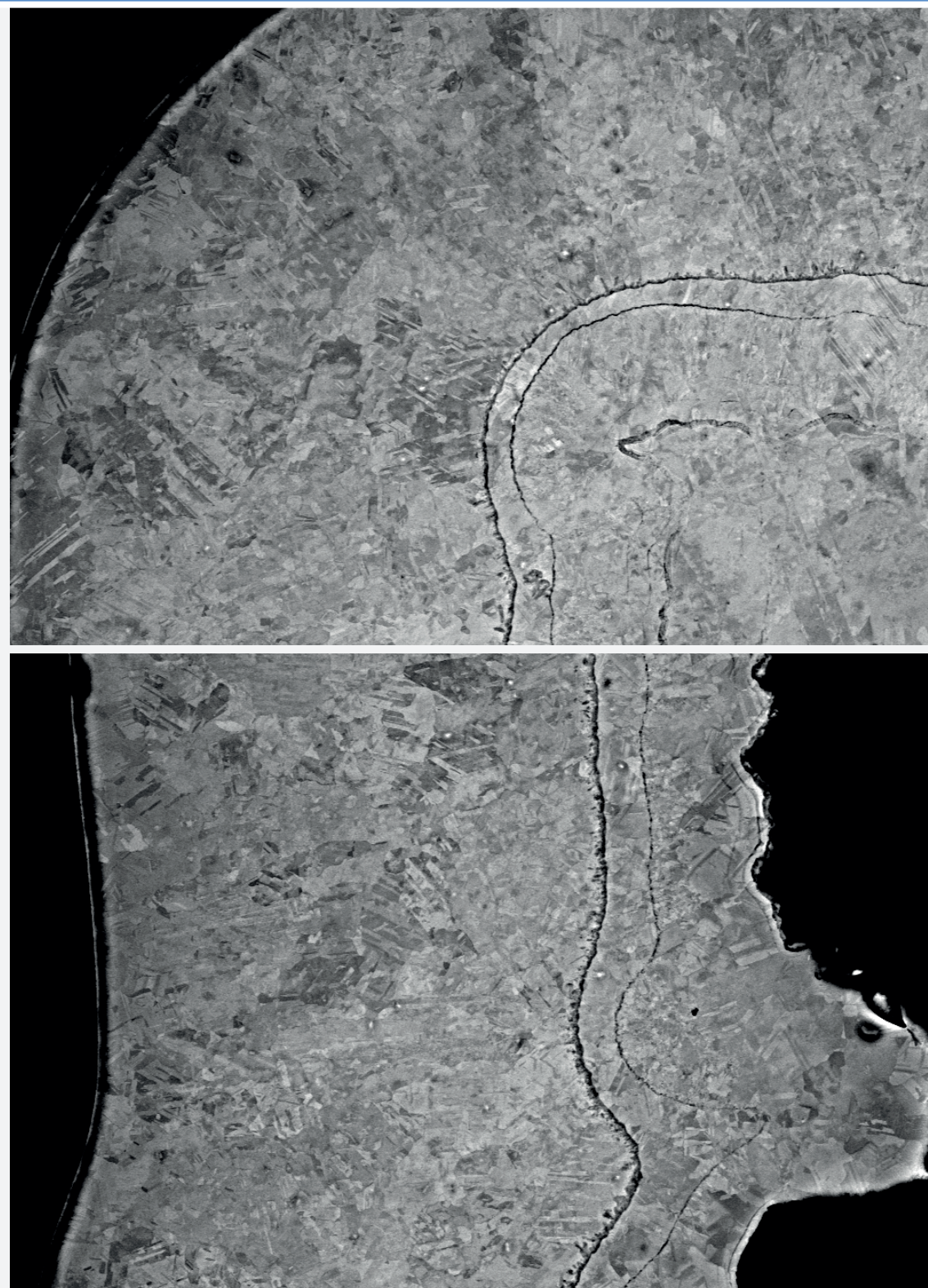
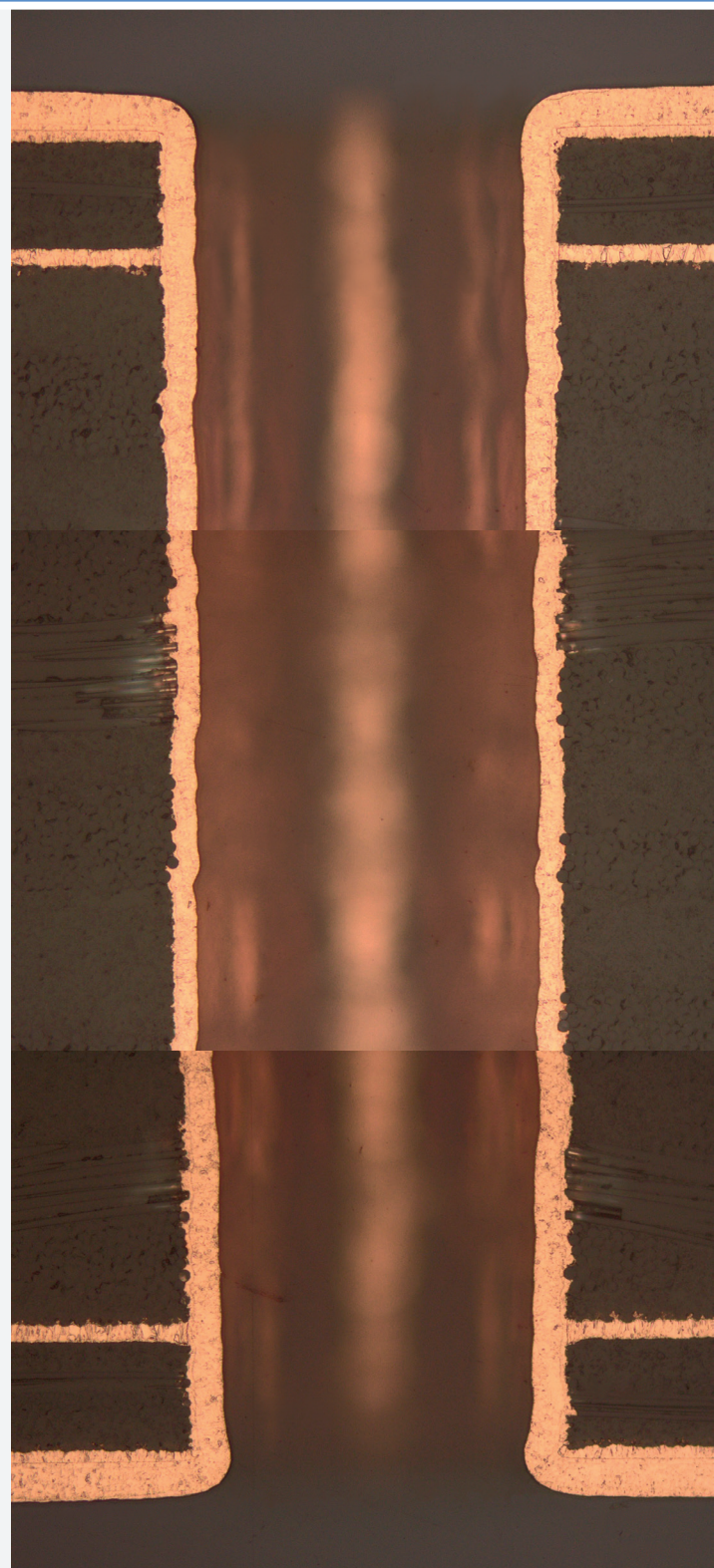


Vertical conformal plating
for highest reliability demands

80% throwing power and no corner flattening at 2.2 A/dm², AR 10:1

Uniform crystal structure of same quality at knee of and centre of hole for best copper characteristics

BMV 100×75 μm with >100% throwing power at 1.6 A/dm²



Conformal plating optimised for reliability in mass production

Cupracid® TP1 PLUS is a conformal copper plating process for soluble anode systems in DC mode. The process was designed for excellent throwing power together with high productivity, up to 3 A/dm². Cupracid® TP1 PLUS can be used in conventional hoist type equipment with air agitation. To meet the requirements of high reliability industries such as Automotive, the copper deposits plated with Cupracid® TP1 PLUS show polygonal shaped crystals with a uniform structure and no signs of grain boundary defects. This results in excellent reliability results such as TCT, IST and solder shock as well as high ductility and tensile strength.

Features and benefits

- Conformal DC plating with soluble anodes in vertical hoist type equipment
- Excellent throwing power for BMV and through holes, e.g. > 80% at AR 12:1
- High corner strength for improved reliability
- Meets standards of reliability tests like solder shock, IST and TCT
- High purity copper deposit with low internal stress for highest reliability
- Fully controllable process with CVS analysis for easy process control